



Material Content Data Sheet



Sales Product Name		BSB104N08NP3 G		Issued		19. July 2018		
MA#		MA001131332						
Package		MG-WDSON-2-6		Weight*		79.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.759	3.46	3.46	34582	34582
leadframe	non noble metal	copper	7440-50-8	74.415	93.29	93.29	932800	932800
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.26		2647	
	noble metal	silver	7440-22-4	0.840	1.05	1.31	10529	13176
plating	non noble metal	nickel	7440-02-0	0.211	0.26	0.26	2647	2647
glue	plastics	epoxy resin	-	0.142	0.18		1777	
	noble metal	silver	7440-22-4	0.871	1.09	1.27	10914	12691
passivation	plastics	epoxy resin	-	0.327	0.41	0.41	4104	4104
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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